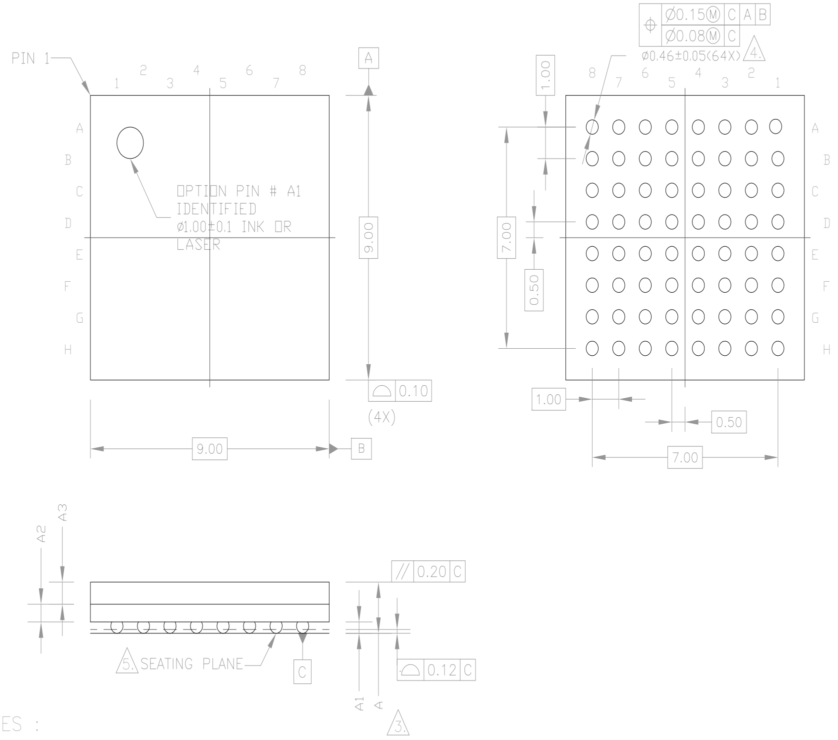
Mechanical Drawing



SYMBOL	MILLIMETER			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.52	1.62	1.72	.059	.064	.069
A1	0.31	0.36	0.41	.012	.014	.016
A2	0.51	0.56	0.61	.020	.022	.024
A3	0.65	0.70	0.75	.026	.028	.029
b	0.41	0.46	0.51	.016	.018	.020
D	8.90	9.00	9.10	.350	.354	.358
D1	7.00 BSC			.276 BSC		
E	8.90	9.00	9.10	.350	.354	.358
E1	7.00 BSC			.354 BSC		
e	1.00 BSC			.039 BSC		

NOTES :

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
2. SOLDER BALL POSITION DESIGNATION PER JESD 95-1, SPP-010.
3. THIS DIMENSION INCLUDES STAND-OFF HEIGHT, PACKAGE BODY THICKNESS AND LID HEIGHT, BUT DOES NOT INCLUDE ATTACHED FEATURES, E.G., EXTERNAL HEATSINK OR CHIP CAPACITORS. AN INTEGRAL HEATSLUG IS NOT CONSIDERED AN ATTACHED FEATURE.
4. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
5. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. ALL DIMENSIONS ARE IN MILLIMETERS.

Microsemi CMPG	DWG. NO.	REV.
TITLE 64L LBGA PACKAGE OUTLINE BODY SIZE :9 X 9 X1.62MM MAX PITCH 1.0MM	CDCA# 22-0008 84-06-128-305	4
	SHEET 1 OF 1	SIZE A4

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